



## Material Content Data Sheet



<b>Sales Product Name</b>		IPL65R130C7		<b>Issued</b>		26. September 2017		
<b>MA#</b>		MA001069336						
<b>Package</b>		PG-VSON-4-1		<b>Weight*</b>		189.34 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.035	3.19	3.19	31875	31875
leadframe	inorganic material	phosphorus	7723-14-0	0.020	0.01		107	
	non noble metal	zinc	7440-66-6	0.081	0.04		427	
	non noble metal	iron	7439-89-6	1.619	0.85		8548	
wire	non noble metal	copper	7440-50-8	65.718	34.71	35.61	347084	356166
	non noble metal	copper	7440-50-8	1.216	0.64	0.64	6420	6420
	encapsulation	organic material	carbon black	1333-86-4	0.215	0.11		1134
plastics		epoxy resin	-	11.060	5.84		58412	
	inorganic material	silicondioxide	60676-86-0	96.103	50.77	56.72	507559	567105
leadfinish	non noble metal	tin	7440-31-5	2.397	1.27	1.27	12662	12662
plating	noble metal	silver	7440-22-4	0.252	0.13	0.13	1331	1331
solder	non noble metal	tin	7440-31-5	0.093	0.05		489	
	noble metal	silver	7440-22-4	0.116	0.06		611	
	non noble metal	lead	7439-92-1	4.419	2.33	2.44	23341	24441
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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